



# 2012 IEEE International Symposium on Radio-Frequency Integration Technology (RFIT2012)

November 21-23, 2012

Singapore

**1<sup>st</sup> Call for Paper**

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### Conference Secretariat:

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With the very successful RFIT symposia held in Singapore and Beijing since 2005, the biennial RFIT symposium will now be held in the even years in November commencing in 2012. This year's RFIT will be back to her beautiful birth city of Singapore. RFIT2012 is a focused yet interdisciplinary forum for microwave and microelectronics technologies. It is co-sponsored by the IEEE Microwave Theory and Techniques Society, IEEE Singapore MTT/AP Chapter, IEEE Singapore SSC Chapter and IEEE Singapore Section.

RFIT provides a forum for the integrated circuit and technology communities to meet and present the latest developments in integrated circuit design, technology and system integration, with emphasis on wireless communication systems and emerging applications such as biology and healthcare, as well as emerging 3D integration technologies. This year's theme is **Integration Technology for Reconfigurable and Programmable SOC/SiP: A Paradigm Shift**.

RFIT will again feature both invited and contributed papers. Distinguished researchers will be invited to deliver keynote speeches and invited talks on technology trends and significant advances. The best papers will be selected from the contributed papers for awards. Both invited papers and contributed papers that are accepted by RFIT2012 will appear in the IEEE Xplore, Science Citation Index (SCI) and Engineering Index (EI). Extended versions of the papers can be published in one issue of the IEEE Transactions on Microwave Theory and Techniques subject to the normal review procedure.

### The topics include, but are not limited to, the following technical areas:

1. **High-number Spec ICs:** High speed/high frequency/high bandwidth/high integration/high performance circuits and systems.
2. **Low-number Spec ICs:** Low power/low voltage/low noise/low complexity circuits and systems.
3. **3D integrations:** On-chip antenna, integrated passive devices, MCM, SiP, TSV, MEMS, etc.
4. **Frequency Generation ICs:** VCOs, PLLs, synthesizers, ADPLL, DDS, frequency dividers, multipliers, etc.
5. **Building Block RFICs:** LNA, PA, mixers, RFE, Si-based MMIC, etc.
6. **Analog and Mixed Signal ICs:** Amplifiers, ADC, DAC, comparators, filters, AGC/VGA, etc.
7. **Device Technologies:** Active/passive devices, packaging, CMOS, SOI, SiGe, GaAs, LDMOS, GaN, reliability, characterization, CAD, modeling, EM simulation, co-simulation, etc.
8. **New Energy IC:** Power management, data converters, sensor and DSP interface IC, new energy vehicle electronics EM and ICs, etc.

### Electronic paper submission and deadlines:

To encourage timely reporting of the latest results and have better opportunities to expand papers for possible journal publications, prospective authors are invited to submit a **3-page** manuscript (both initial submission and final manuscript, if accepted) in English and in IEEE PDF eXpress format. The manuscript should emphasize original contributions and key findings, including figures, diagrams and results from both simulations and measurements. References should be clearly cited and up-to-date. If accepted, the manuscript needs to be resubmitted in exactly the required format and will be published in IEEE Xplore. By submitting a manuscript, the authors promise that, if accepted, at least one of them will attend RFIT2012 with full registration.

Manuscript template with format and style guides is available at [www.ieee-rfit.org](http://www.ieee-rfit.org).

### **Manuscript submission deadline:**

Notification of Acceptance:  
Submission of final manuscript:

**August 6, 2012 (Monday)**

September 27, 2012 (Thursday)

October 26, 2012 (Friday)

### **Exhibitions:**

Exhibition of company products are solicited for the areas related to the symposium. Interested parties should contact the Exhibition Chair or Conference Secretariat.

